

SOT618-1

plastic thermal enhanced very thin quad flat package; no leads; 40 terminals; body 6 x 6 x 0.85 mm

25 November 2022

Package information

1 Package summary

Terminal position code	Q (quad)
Package type descriptive code	HVQFN40
Package type industry code	HVQFN40
Package style descriptive code	HVQFN (thermal enhanced very thin quad flatpack; no leads)
Package body material type	P (plastic)
JEDEC package outline code	MO-220
Mounting method type	S (surface mount)
Issue date	22-11-2022
Manufacturer package code	SOT618

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	5.9	6	6.1	mm
package width	5.9	6	6.1	mm
seated height	-	0.85	1	mm
nominal pitch	-	0.5	-	mm
actual quantity of termination	-	40	-	



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2 Package outline

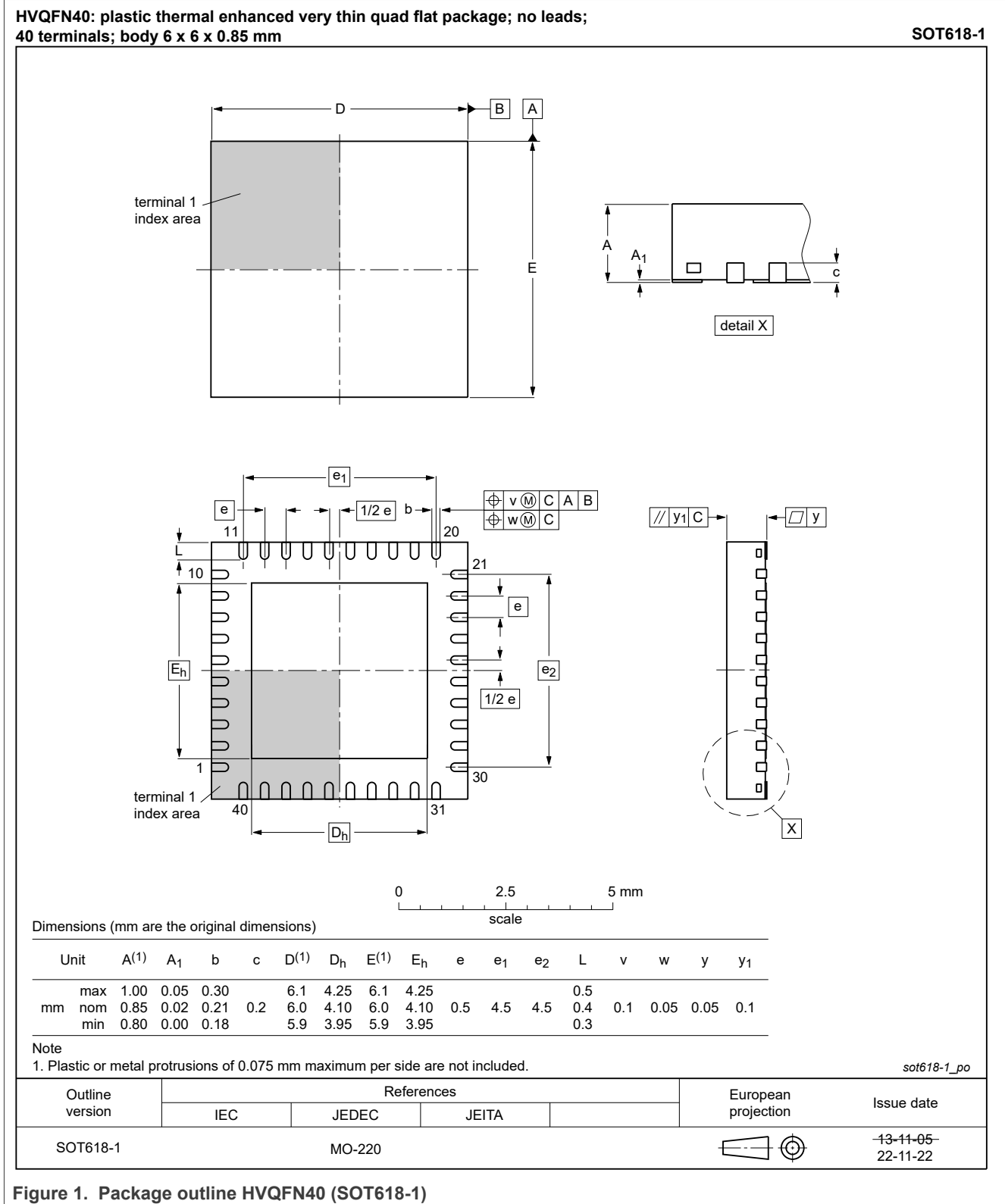


Figure 1. Package outline HVQFN40 (SOT618-1)

3 Soldering

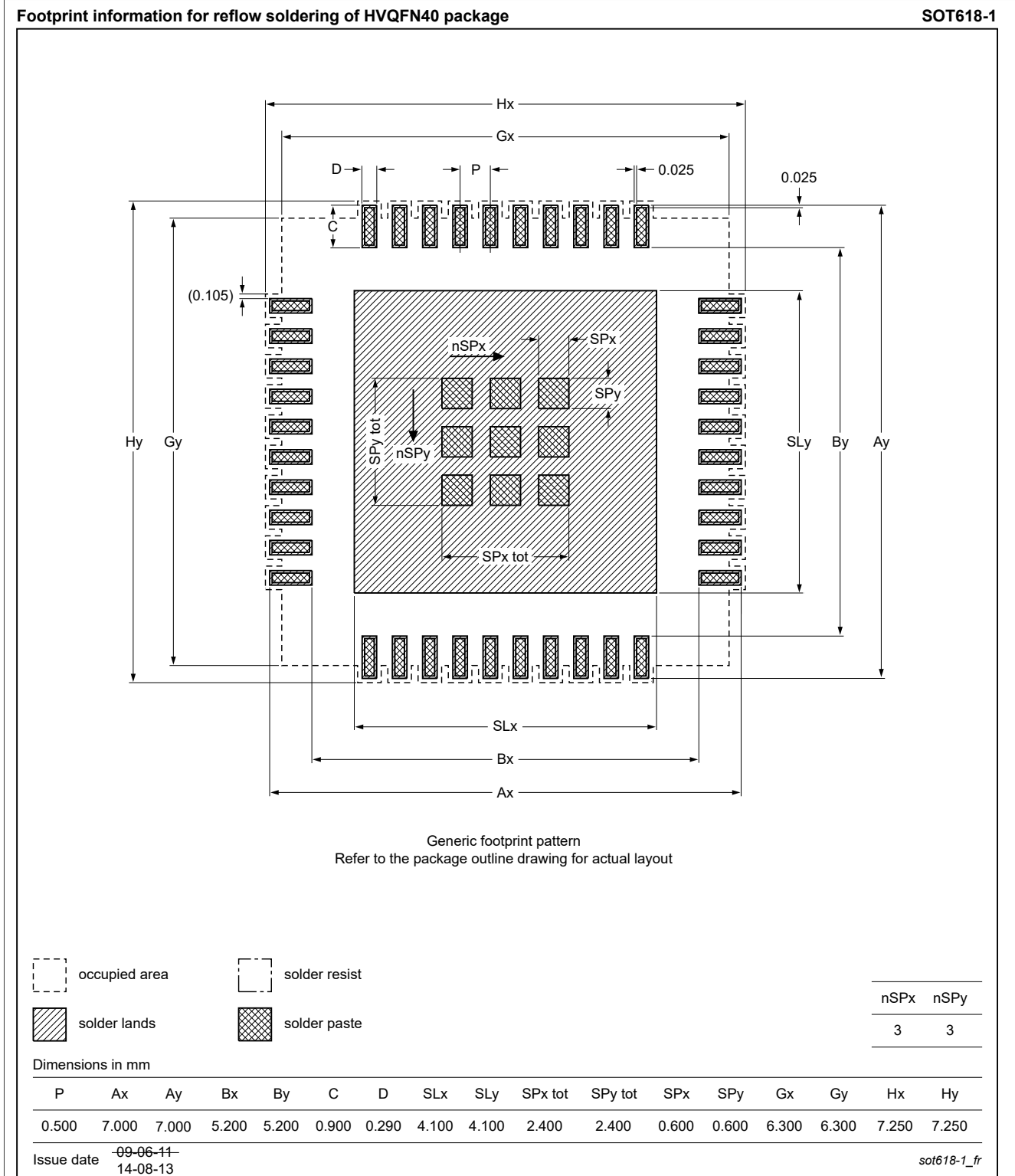


Figure 2. Reflow soldering footprint for HVQFN40 (SOT618-1)

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4 Legal information

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